

Special Issue on Advanced Technologies for Remote Sensing and Geospatial Analysis

Call for Papers

With the explosive growth of sensor technology and the ubiquity of connected, we have moved to a data-rich information society. Much of this data has both spatial and temporal components. Artificial intelligence and machine learning have tremendous potential for discovering interesting patterns and knowledge from massive amounts of data. In particular, geospatial artificial intelligence (GeoAI) has been of great help in answering spatial questions in remote sensing, UAV, GIS, cartography, and mapping. It enables analysts to extract deeper insights through spatially enabled analytical methods and algorithms. This special issue aims to bring together a community of researchers and practitioners who develop advanced technologies for remote sensing and geospatial analysis. Topics of interest include but are not limited to:

- Novel remote sensing techniques and applications
- Unmanned aerial vehicle (UAV) applications
- IoT Sensors
- Analytics for big geospatial data
- Indoor and outdoor location-based services
- Structural health monitoring
- Resilient and smart cities
- Land use/land cover
- LiDAR
- Visualization of massive geospatial data
- Novel applications of GeoAI in disaster management, public health, climate change, and transportation

Submission due date: April 30, 2022

Publication date (planned): June 2022

Journal website: <http://myukk.org/>

Guest Editors:

Prof. Dong Ha Lee, PhD

Department of Civil Engineering, Kangwon National University, Chuncheon 24341, Republic of Korea

E-Mail: geodesy@kangwon.ac.kr

Interests: Geodesy, Surveying, Geo-spatial information, Natural hazard analysis

Myeong Hun Jeong, PhD

Department of Civil Engineering, Chosun University, Gwangju 61452, Republic of Korea

E-Mail: mhjeong@chosun.ac.kr

Interests: GeoAI, Geographic Information Science, Geospatial Data Science, Decentralized Spatial Computing, Geosensor Networks

Submit to:

1. Online Manuscript Submission System (<https://myukk-org.ssl-xserver.jp/form/>) or

2. Email to MYU K.K. (myukk@myu-inc.jp)

(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in Sensors and Materials format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors will bear the proofreading fee (JPY 10000–30000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of Sensors and Materials

MYU K.K.

1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan

Tel: +81-3-3827-8549, Fax: +81-3-3827-8547

E-mail: myukk@myu-inc.jp

